

IN THE CLAIMS:

Claims 2-6, and 9-14 have been amended herein. All of the pending claims 1 through 14 are presented below. This listing of claims will replace all prior versions and listings in the application. Please enter these claims as amended.

1. (Original) A method for forming an interposer substrate, comprising:
providing a substantially planar substrate;
forming an elongated interconnect slot comprising a plurality of longitudinally adjacent segments separated by at least one transversely extending crosspiece.
2. (Currently Amended) The method of claim 1, further ~~including~~ comprising forming the interconnect slot by milling through the substrate and the at least one transversely extending crosspiece comprises at least one unmilled portion of the substrate lying intermediate opposing ends of the interconnect slot.
3. (Currently Amended) The method of claim 2, further comprising producing filleted side edges on the at least one transversely extending crosspiece during the milling.
4. (Currently Amended) The method of claim 1, wherein forming ~~an~~ the elongated interconnect slot comprises forming a unitary elongated interconnect slot and forming the at least one transversely extending crosspiece by bonding a segment of material transversely across the interconnect slot at a location intermediate opposing ends thereof.
5. (Currently Amended) The method of claim 4, wherein forming the at least one transversely extending crosspiece comprises forming a tape segment coated with an adhesive on opposing sides thereof and adhering the tape segment to a surface of the substantially planar substrate.

6. (Currently Amended) The method of claim 1, wherein forming ~~an~~ the elongated interconnect slot comprises forming a unitary elongated interconnect slot, forming an "I"-shaped segment of material and bonding a head portion of the "I"-shaped segment to the substrate on one side of the interconnect slot and a foot portion of the "I"-shaped segment to the substrate on an opposing side of the interconnect slot with a body portion of the "I"-shaped segment extending transversely thereacross to form the at least one transversely extending crosspiece.

7. (Original) The method of claim 6, further comprising forming the "I"-shaped segment as a film having an adhesive coating on opposing sides thereof.

8. (Original) The method of claim 6, further comprising forming the "I"-shaped segment as a substantially rigid plastic segment.

9. (Currently Amended) The method of claim 1, wherein forming ~~an~~ the elongated interconnect slot comprises forming a unitary elongated interconnect slot, forming a "T"-shaped element having a body and a cap, extending the body into the interconnect slot in contact with opposing sides thereof and bonding legs of the cap extending transversely to the interconnect slot over a surface of the substrate thereto to form the at least one transversely extending crosspiece.

10. (Currently Amended) The method of claim 1, wherein forming ~~an~~ the elongated interconnect slot comprises forming a unitary elongated interconnect slot, forming a tape segment of a polymeric material containing a reinforcement material, disposing the tape segment transversely across the interconnect slot and bonding the tape segment to a surface of the substrate.

11. (Currently Amended) The method of claim 1, wherein forming ~~an~~ the elongated interconnect slot comprises forming a unitary elongated interconnect slot, interposing a bar of material transversely between opposing sides of the interconnect slot and bonding the bar thereto.

12. (Currently Amended) The method of claim 1, further ~~including~~ comprising forming the elongated interconnect slot to a length of about 67% or more of a length of the substrate.

13. (Currently Amended) The method of claim 12, further ~~including~~ comprising forming the elongated interconnect slot to a length of about 70 to 80% of a length of the substrate.

14. (Currently Amended) The method of claim 1, further ~~including~~ comprising locating the at least one transversely extending crosspiece substantially at a longitudinal midpoint of the interconnect slot.